

描述 / Descriptions

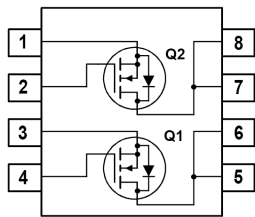
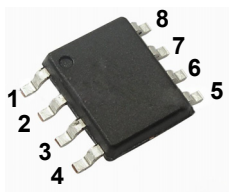
SOP-8 塑封封装 N 沟道 Power Trench MOS 双场效应管。
 Dual N-Channel Power Trench MOSFET in a SOP-8 Plastic Package.

特征 / Features

- ◆ 优化电池保护电路，允许工作电压范围宽： $\pm 10 V_{GSS}$ ，低栅极电荷。内置双 MOSFET。无卤产品。
- ◆ Optimized for use in battery protection circuits, $\pm 10 V_{GSS}$ allows for wide operating voltage range, Low gate charge. Built-in dual MOSFET. Halogen-free Product.

用途 / Applications

电池保护，负载开关，电源管理。
 Battery protection, Load Switch, Power management.

内部等效电路 / Equivalent Circuit**引脚排列 / Pinning**

PIN1:S2 PIN 2:G2 PIN 3 : S1 PIN 4 : G1

PIN5、PIN 6:D1 PIN 7、PIN 8 : D2

放大及印章代码 / h_{FE} Classifications & Marking

见印章说明。See Marking Instructions.

极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Drain-Source Voltage	V_{DSS}	20	V
Gate-Source Voltage	V_{GS}	±10	V
Drain Current– Continuous ^(note 1a)	I_D	6.5	A
Drain Current–Pulsed		20	A
Power Dissipation for Dual Operation	P_D	2.0	W
Power Dissipation for Single Operation ^(note 1a)		1.6	W
Power Dissipation for Dual Operation ^(note 1b)		1.0	W
Power Dissipation for Single Operation ^(note 1c)		0.9	W
Thermal Resistance, Junction-to-Ambient ^(note 1a)	$R_{\theta JA}$	78	°C/W
Thermal Resistance, Junction-to case ^(note 1)	$R_{\theta JC}$	40	°C/W
Operating and Junction Temperature Range	T_j T_{stg}	-55~150	°C

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V$ $I_D=250\mu A$	20			V
Breakdown Voltage Temperature Coefficient	$\Delta BV_{DSS}/\Delta T_J$	$I_D=250\mu A$ Referenced to 25°C		14		mV/°C
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=16V$ $V_{GS}=0V$			1.0	μA
Gate-Body Leakage Current Forward	I_{GSS}	$V_{GS}=\pm 8.0V$ $V_{DS}=0V$			±100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ $I_D=250\mu A$	0.5	1.0	1.5	V
Gate Threshold Voltage Temperature Coefficient	$\Delta V_{GS(th)}/\Delta T_J$	$I_D=250\mu A$ Referenced to 25°C		-3.0		mV/°C
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=4.5V$ $I_D=6.5A$		19	24	mΩ
		$V_{GS}=4.5V$ $I_D=6.5A$ $T_J=125^\circ C$		27	34	
		$V_{GS}=2.5V$ $I_D=5.4A$		23	30	
On-State Drain Current	$I_{D(on)}$	$V_{DS}=5.0V$ $V_{GS}=5.0V$	15			A
Forward Transconductance	g_{FS}	$V_{DS}=5.0V$ $I_D=3.0A$		11		S

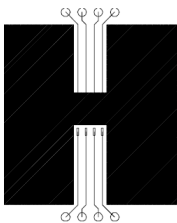
电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Input Capacitance	C _{iss}	V _{DS} =10V V _{GS} =0V f=1.0MHz		700		pF
Output Capacitance	C _{oss}			175		
Reverse Transfer Capacitance	C _{rss}			85		
Turn-On Delay Time	t _{d(on)}	V _{DD} =10V I _D =1.0A R _{GEN} =6Ω V _{GS} =4.5V		8	16	ns
Turn-On Rise Time	t _r			10	18	
Turn-Off Delay Time	t _{d(off)}			18	29	
Turn-Off Fall Time	t _f			5.0	10	
Total Gate Charge	Q _g	V _{DD} =10V I _D =3.0A V _{GS} =4.5		7.0	10	nC
Gate-Source Charge	Q _{gs}			1.2		
Gate-Drain Charge	Q _{gd}			1.9		
Maximum Continuous Drain-Source Diode Forward Current	I _S				1.3	A
Drain-Source Diode Forward Voltage	V _{SD}	I _S =1.3A (note2) V _{GS} =0V		0.65	1.2	V

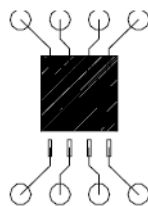
Notes:

1. R_{θJA} is the sum of the junction-to-case and case-to-ambient resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{θJC} is guaranteed by design while R_{θJA} is determined by the user's board design.

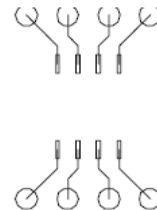
a) 78°C/W when mounted on a 0.5 in² pad of 2 oz. copper.



b) 125°C/W when mounted on a 0.02 in² pad of 2 oz. copper.



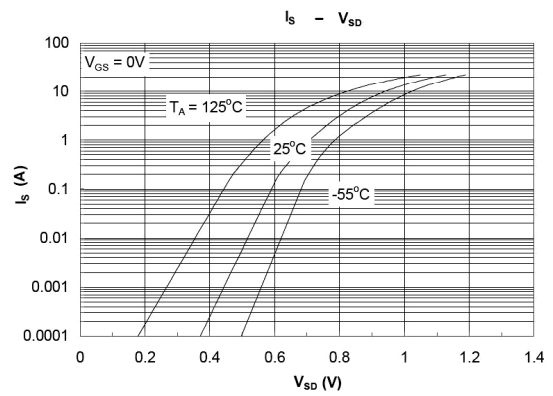
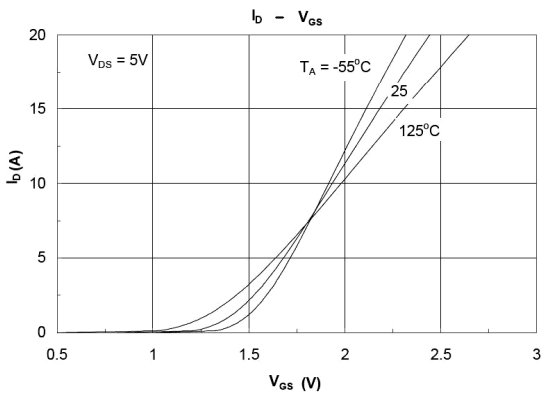
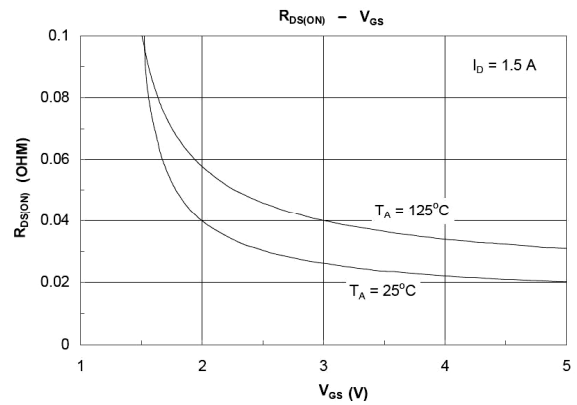
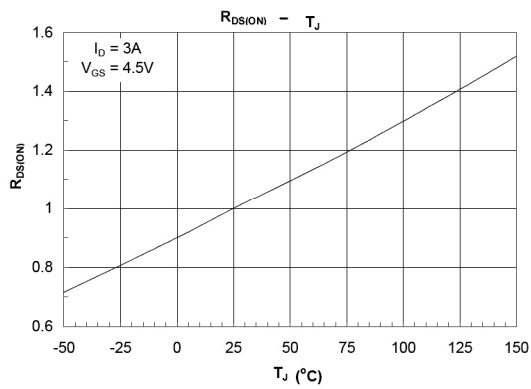
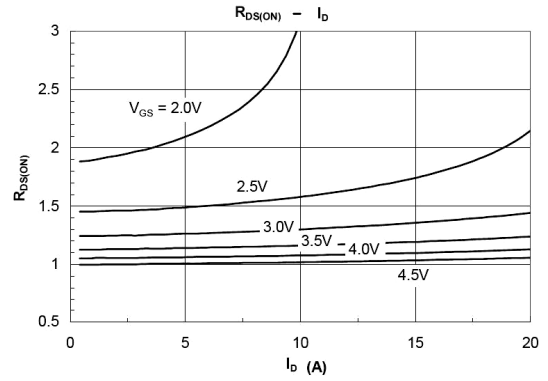
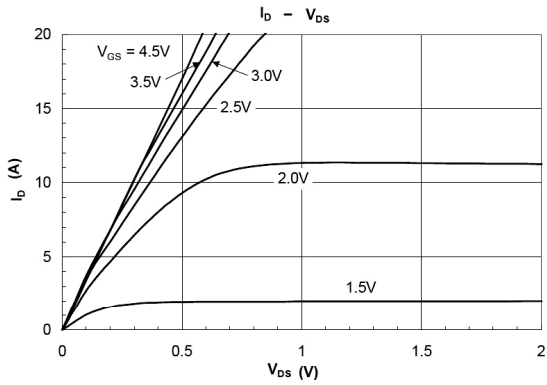
c) 135°C/W when mounted on a minimum pad.



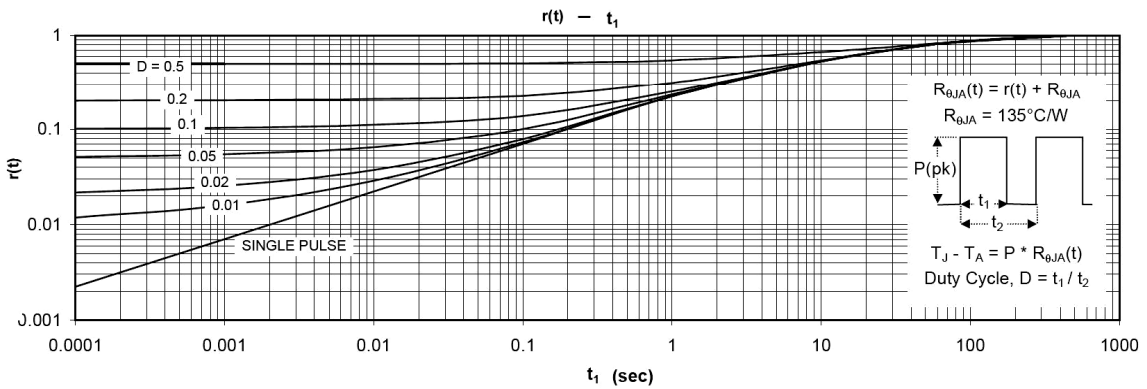
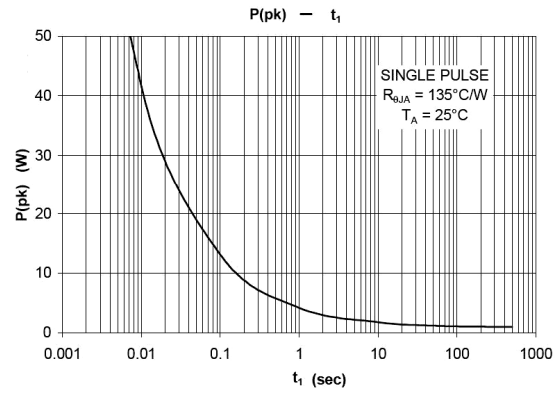
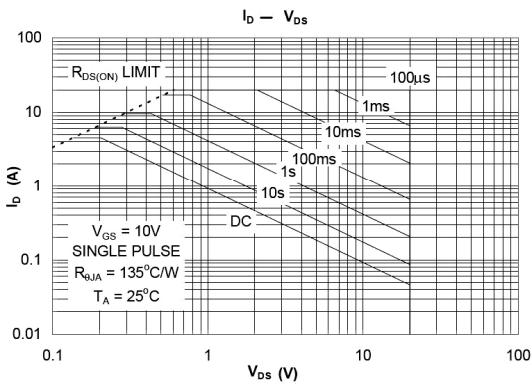
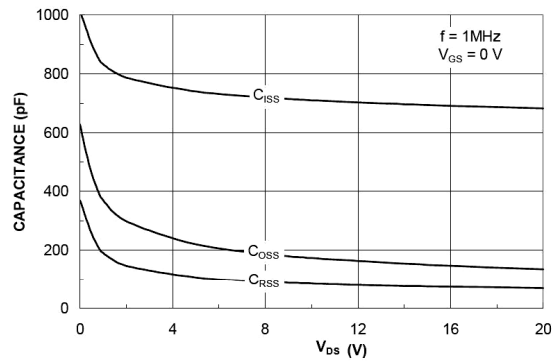
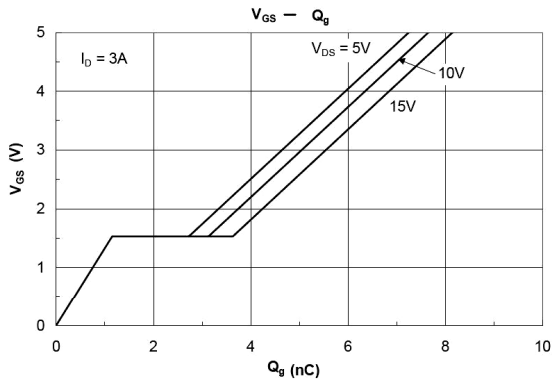
Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%

电参数曲线图 / Electrical Characteristic Curve



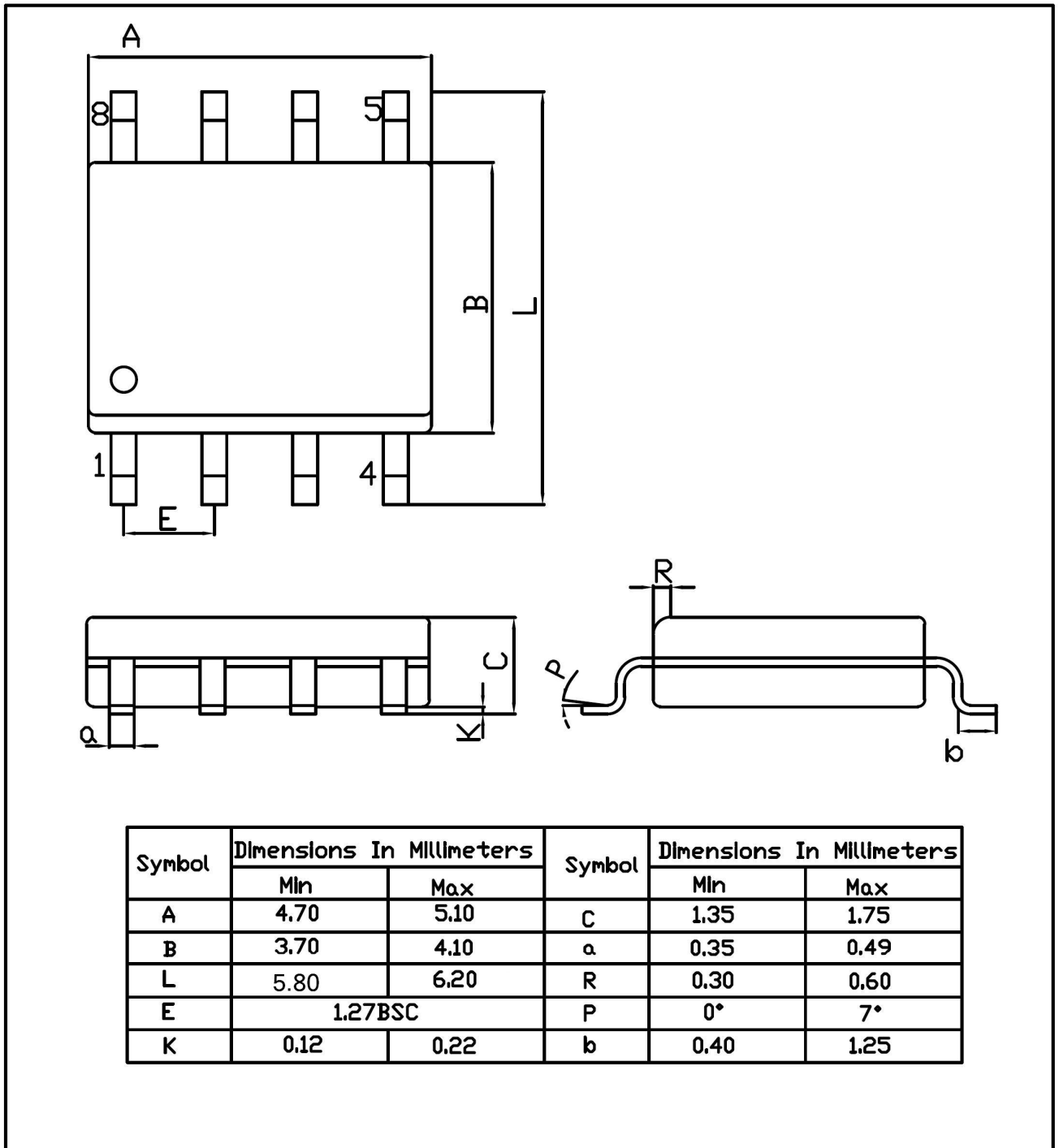
电参数曲线图 / Electrical Characteristic Curve



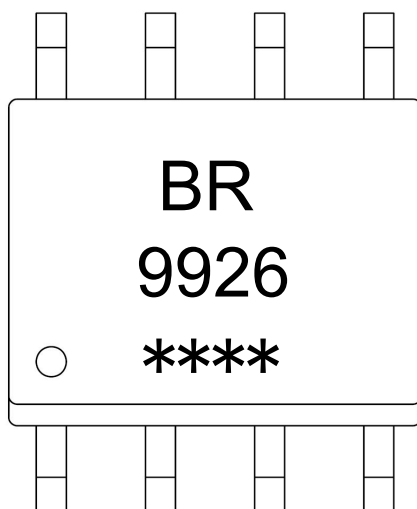
外形尺寸图 / Package Dimensions

SOP-8

Unit:mm



印章说明 / Marking Instructions



说明：

BR： 为公司代码

9926： 为型号代码

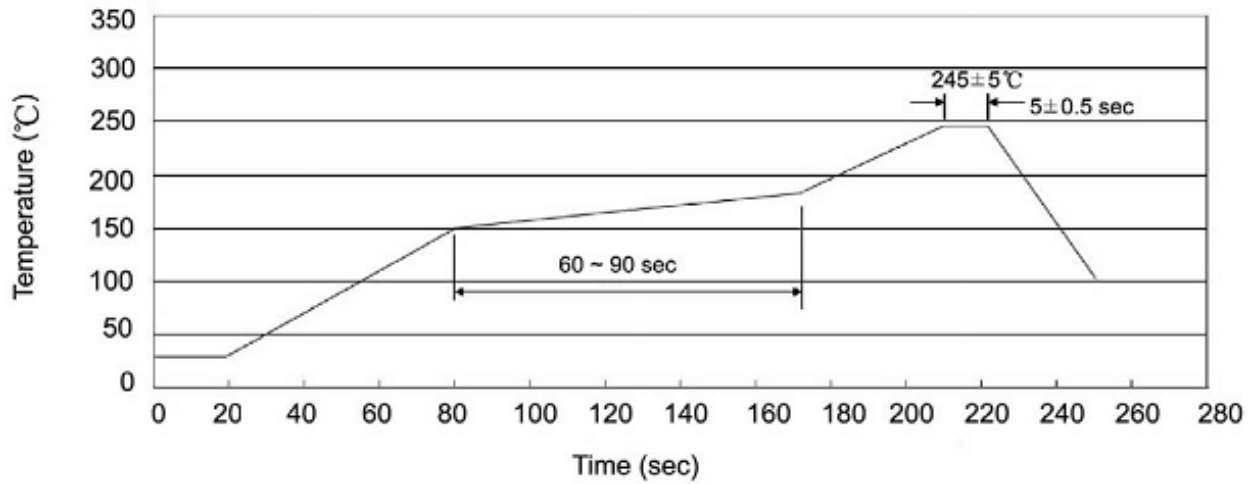
****： 为生产批号代码，随生产批号变化

Note:

BR: Company Code.

9926 : Product Type.

****: Lot No. Code, code change with Lot No.

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)


说明：

- 1、预热温度 150~180°C，时间 60~90sec；
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec；
- 3、焊接制程冷却速度为 2~10°C/sec.

Note:

- 1.Preheating:150~180°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOP/ESOP-8	4,000	2	8,000	6	48,000	13" ×12	360×360×50	380×335×366

使用说明 / Notices